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S/N 10/607,782

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Sabina J. Houle	Examiner:	Matthew Warren
Serial No.:	10/607,782	Group Art Unit:	2815
Filed:	June 27, 2003	Docket No.:	884.860US1
Title:	LIQUID SOLDER THERMAL INTERFACE MATERIAL CONTAINED WITHIN A COLD-FORMED BARRIER AND METHODS OF MAKING SAME		
Assignee:	Intel Corporation	Customer No:	21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on November 24, 2004. Please amend the above-identified patent application as follows.

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